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PATENT ABSTRACTS OF JAPAN(21) Application number: **09305885**(51) Intl. Cl.: **B24B 37/00**(22) Application date: **07.11.97**

(30) Priority:		(71) Applicant: NIKON CORP
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**(54) CMP POLISHING PAD
AND POLISHING DEVICE
USING IT**

(57) Abstract:

PROBLEM TO BE SOLVED: To provide a polishing pad which has the optimum hardness corresponding to the hardness of a polished object, without reducing the property of the polishing pad, and a polishing device using it.

SOLUTION: A CMP polishig pad 10 mainly contains A and B components, including bisphenol A epoxy resin, novolak epoxy resin, bisphenol F epoxy resin, or these polymer and these deformed epoxy resin, aromatic amines, aromatic acid anhyddride, imidazols, or these polymer and these deformed hardening agent, monoepoxide, polyepoxide, polythiol, polyole, polycarboxyl compound, urethane prepolymer, and flexible granting agent of block urethane prepolymer, the surface hardness being 2.5-40 at a

epoxy

Vickers hardness.

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